Cross Society Special Issue (ISCAS & IFETC) on Flexible Hybrid Electronics: Advancing Next-Generation Applications

The scope of this Special Journal Issue includes materials and interface engineering, multi-physics simulation tools, system integration and packaging, interfacing circuits based on thin film transistors, optimization of hybrid system, and prototypes of flexible hybrid electronics (FHE). Authors are invited to submit papers on the process development, system simulations, signal/power/thermal intergrity, flexible-rigid interfacing and energy harvesting aspects of potential FHE applications.

Topics
- Applications based on flexible hybrid electronics
- Prototype and key components of FHE system
- Simulation methodologies for hybrid system
- Advanced Packing for hybrid system
- Flexible-rigid interface engineering
- Multi-physics modeling
- Stretchable/Shrinkable Sensors and Electronics
- Hybrid Systems-in-Foil
- Biomedical sensing devices
- Electronic textile/paper/skin
- Flexible/Printable Electronics in context with Circular Economy
- Organic/Inorganic/Hybrid Flexible Sensors and Electronics
- Emerging Materials for Flexible and Printable Systems
- Printable batteries, energy harvesters
- Wearable sensors
- Sensors for health monitoring
- Printable displays, lighting sources
- Smart tags, RFID tags, etc.
- Modeling of printable sensors
- Manufacturing Techniques (including Printing)
- 3D printing

Important dates
- July 2024: Call for Papers (to appear in IEEE Journal on Flexible Electronics)
- October 31, 2024: Deadline for Paper Submission
- December 2024: Completion of First Review
- January 2025: Completion of Final Review
- March 2025: Publication

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Submission and Peer Review of Papers
All papers shall undergo the standard IEEE J-FLEX peer-review process. Manuscripts must be submitted online, via the IEEE Journal on Flexible Electronics Author portal, see https://ieeexplore.ieee.org/journal/jflex. When submitting, please indicate in the “Manuscript Type” roll down menu, and also by e-mail to Mansi Kukreti, m.kukreti@ieee.org, that the paper is intended for the CAS FHE Special Issue. Authors are particularly encouraged to suggest names of potential reviewers for their manuscripts in the space provided for these recommendations in Manuscript Central. For manuscript preparation and submission, please follow the guidelines in the Information for Authors at the IEEE J-FLEX web page, https://ieeexplore.ieee.org/guidelines-for-authors/.